

Thu, Nov 13, 2008 at 3:42 PM

Intelleflex Corporation, FCC ID: VBLIB500, Assessment NO.: AN08T8583, Notice#1

2 messages

tim.dwyer@ccsemc.com <tim.dwyer@ccsemc.com> To: tom@tncokenias.org Cc: tim.dwyer@ccsemc.com

Hi Tom,

The application review is complete. Please reply to the following issues.

Q1: Please provide internal photos showing the inside of the new enclosure.

Q2: Please provide a confirming statement that the circuit board has not changed except as indicated in the cover letter.

Q3: Please provide a confirming statement that the internal photo exhibits and other exhibits from previous filings continue to be accurate representations of the circuit board and device in general

Q4: The original application MPE distance was 21.3 cm and the user manual specified 22 cm separation. In this application, the MPE distance has increased to 26.3 cm. Please provide a revised manual with the new MPE distance.

The items indicated above must be submitted before processing can continue on the above referenced application. Failure to provide the requested information within 30 days of the original e-mail date may result in application dismissal and forfeiture of the filing fee. Also, please note that partial responses increase processing time and should not be submitted. Any questions about the content of this correspondence should be directed to the e-mail address listed below the name of the sender.

Best regards,

Tim Dwyer Technical Reviewer

Thomas Cokenias <tom@tncokenias.org>

To: "<tim.dwyer@ccsemc.com>" <tim.dwyer@ccsemc.com> Cc: Russell Shikami <rshikami@intelleflex.com>, Dean Kawaguchi <dkawaguchi@intelleflex.com> Thu, Dec 11, 2008 at 3:08 PM

Hi Tim,

Answers follow questions. If you need further information to issue this grant, please let me know and I will get it to you as soon as possible.

best regards

Tom

On Nov 13, 2008, at 12:42 PM, <<u>tim.dwyer@ccsemc.com</u>> <<u>tim.dwyer@ccsemc.com</u>> wrote:

Hi Tom,

The application review is complete. Please reply to the following issues.

Q1: Please provide internal photos showing the inside of the new enclosure. ANS1 Photos attached.

Q2: Please provide a confirming statement that the circuit board has not changed except as indicated in the cover letter. ANS2 The circuit board has not changed except for what is indicated in the cover letter

Q3: Please provide a confirming statement that the internal photo exhibits and other exhibits from previous filings continue to be accurate representations of the circuit board and device in general

ANS 3 The internal photo exhibits and other exhibits from the previous WJ Communications filing are representative of and applicable to the circuit board and the device being marketed by Intelleflex.

Q4: The original application MPE distance was 21.3 cm and the user manual specified 22 cm separation. In this application, the MPE distance has increased to 26.3 cm. Please provide a revised manual with the new MPE distance.

ANS 4 The user manual has been updated: distances are listed as 27 cm (11 in) on pages 23 and 24 of the updated manual, attached.

The items indicated above must be submitted before processing can continue on the above referenced application. Failure to provide the requested information within 30 days of the original e-mail date may result in application dismissal and forfeiture of the filing fee. Also, please note that partial responses increase processing time and should not be submitted. Any questions about the content of this correspondence should be directed to the e-mail address listed below the name of the sender.

Best regards,

Tim Dwyer Technical Reviewer

2 attachments	
1 В500 1787К	
<mark>™</mark> Case 93K	